



COSMOPLENE® SF226

CHARACTERISTICS

COSMOPLENE SF226 is Polypropylene Homopolymer resin developed for Biaxially oriented films for dielectric applications used in capacitors.

COSMOPLENE SF226 is a high purity resin with low ash content. It does not contain slip, antiblock, nucleating and antistatic additives.

APPLICATIONS

COSMOPLENE SF226 is specially designed for biaxially oriented films for dielectrical films used in capacitors.

PHYSICAL PROPERTIES

ITEM	UNIT	SF226	TEST METHOD
Melt Flow Rate	g/10 mins	3.0	ASTM D1238
Density	g/cm ³	0.905	ASTM D792
Melting Point	°C	168	TPC METHOD
Crystallization Point	°C	116	TPC METHOD
Isotactic Index	%	98	TPC METHOD
Total Ash content	ppm	< 30	TPC METHOD

- The figures presented are typical laboratory averages, only for reference.
- The information is based on our current knowledge, is subjected to continuous updates and is intended to suggest/ recommend product applications and to provide typical data on the related properties. It should not therefore be construed as guaranteeing any specific property of the product. TPC makes no warranty of any kind, expressed or implied, regarding the accuracy of these data.

